

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	: 10/809,182	Confirmation No. 6820
Applicant(s)	: UMENO, Kuniharu et al.	
Filed	: 03/25/2004	
TC/A.U.	: 1712	
Examiner	: Robert E. Sellers	
Title	: Resin Composition for Encapsulating Semiconductor Chip and Semiconductor Device Therewith	
Docket No.	: 033036.076	
Customer No.	: 25461	

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

SUPPLEMENTAL AMENDMENT

Further in response to the Office Action of June 28, 2006, please amend the above-identified application as follows:

Amendments to the specification are reflected beginning on page 2.

Remarks/Arguments begin on page 9 of this paper.